

HP Z24q G3



Estimated impact

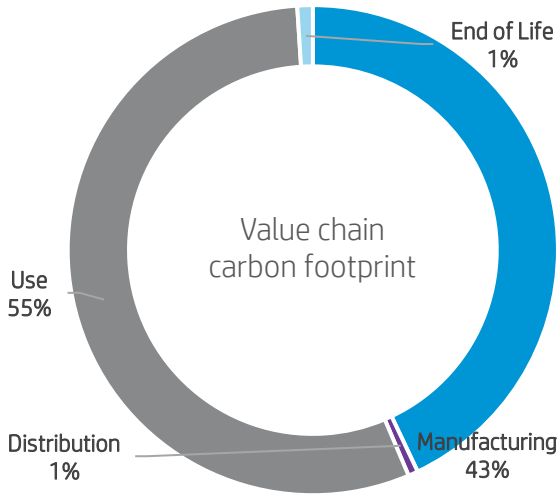
251
kg CO₂ eq.



As part of HP’s commitment to continually improve the environmental performance of our products, we utilize product carbon footprinting (PCF) to better understand environmental impacts that occur at different stages of the product life cycle. A product carbon footprint is defined as the total amount of greenhouse gases emitted directly and indirectly by a product over its lifetime. Our product carbon footprints include full value chain emissions, which incorporates carbon emissions due to raw materials extraction, manufacturing, distribution, use, and product end-of-use.

The information provided here represents the lifecycle carbon footprint of an industry-average display with the specifications listed in Assumptions table.

GHG Emissions



Manufacturing Breakout

Display	51.2%
Chassis	28.2%
Mainboard and other boards	14.3%
Others*	3.3%
Power Supply Unit & External Cables	1.6%
Packaging	1.5%

HP’s environmental impact calculations are done in accordance with ISO 14040/44. All estimates of impact results are uncertain, resulting largely from data limitations and data quality. To mitigate this uncertainty, HP has developed HP-specific tools that use a combination of HP processes and product data, as well as high-quality lifecycle assessment data. HP strives to provide the most accurate environmental impact results but uncertainty will never be completely minimized and results should be considered accordingly.

Assumptions

Lifetime of product (years)	5
Use location	North America
Use energy demand (kWh/year)	51.99
Product weight (kg)	5.3
Screen size (in)	23.8
Final manufacturing location	China

Additional product environmental performance

Additional information about HP’s carbon footprinting program can be found in HP’s yearly Sustainability Report, which is available on the HP Sustainability website.

The site also contains IT Eco Declarations, which provide product-specific environmental information, as well as information on HP’s product recycling programs.

* Others section includes assembly energy, other subassemblies and all subassemblies packaging and transport

Learn more at

[HP’s Sustainability Website](#)

